

1-2102430-2 ✓ ACTIVE

Mezalok | AMP Mezalok

TE Internal #: 1-2102430-2

PCB Mount Receptacle, Vertical, Board-to-Board, 320 Position, 1.27 mm [.05 in] Centerline, Gold (Au), Surface Mount - Solder Ball, Signal, AMP Mezalok

[View on TE.com >](#)



Connectors > PCB Connectors > PCB Headers & Receptacles > High-speed Mezzanine Connector: Pin & Socket Connector



PCB Connector Type: **PCB Mount Receptacle**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **320**

Number of Rows: **8**

[All High-speed Mezzanine Connector: Pin & Socket Connector \(33\)](#)

Features

Product Type Features

PCB Connector Type	PCB Mount Receptacle
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly

Configuration Features

Board-to-Board Configuration	Parallel
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	320
Number of Rows	8

Electrical Characteristics

Operating Voltage	250 VAC
Dielectric Withstanding Voltage (Max)	750 VAC

Signal Characteristics

Data Rate	10 Gb/s
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Body Features

Primary Product Color	Natural
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Contact Features

Contact Underplating Material	Nickel
Contact Mating Area Plating Material Thickness	.076 μm [30 μin]
Mating Tab Width	.43 mm[.017 in]
Contact Shape & Form	Square
Contact Layout	Matrix
Contact Base Material	Beryllium Copper
Mating Tab Thickness	.46 mm[.017 in]
PCB Contact Termination Area Plating Material	Tin-Silver-Copper
Contact Mating Area Plating Material Finish	Bright
Contact Mating Area Plating Material	Gold (Au)
Contact Type	Socket
Contact Current Rating (Max)	1.5 A

Termination Features

Termination Method to PCB	Surface Mount - Solder Ball
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Mechanical Attachment

Mating Alignment Type	Polarizing Rib, Self-Aligning (Alignment Free)
PCB Mount Retention Type	Solder Ball
PCB Mount Alignment Type	None
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Mating Alignment	With

Housing Features

Mating Entry Location	Top
Housing Material	LCP
Centerline (Pitch)	1.27 mm[.05 in]

Dimensions

Row-to-Row Spacing	1.27 mm[.05 in]
Stack Height	18 mm[.709 in]



PCB Thickness (Recommended)	2.36 mm [.093 in]
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Usage Conditions

Operating Temperature Range	-55 – 125 °C [-67 – 257 °F]
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Operation/Application

Assembly Process Feature	Pick and Place Cover
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Circuit Application	Signal
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Packaging Features

Packaging Method	Pocket Tape
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Reflow solder capable to 260°C
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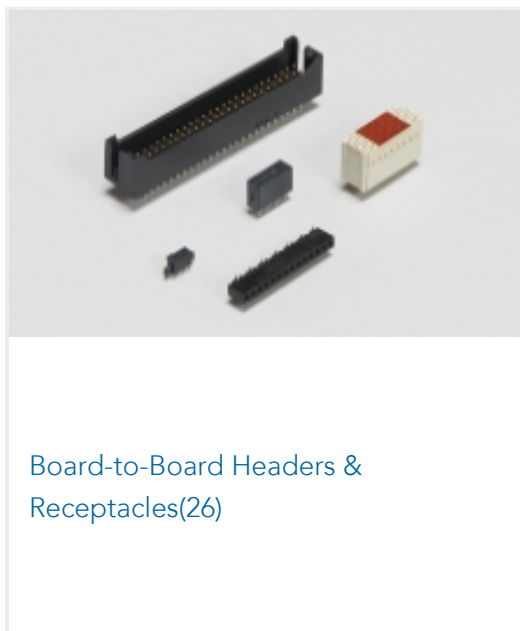
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

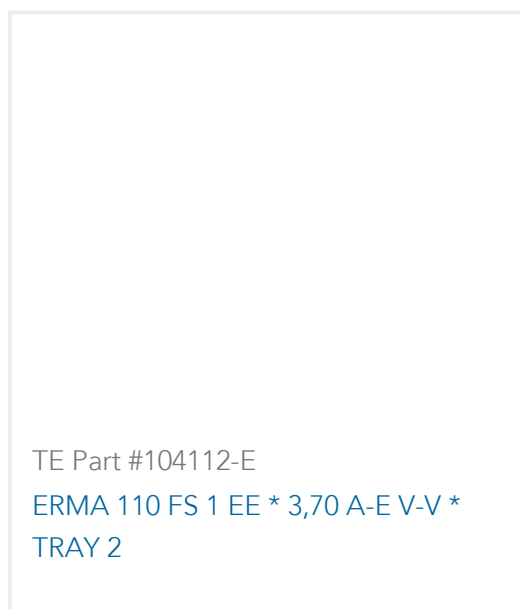
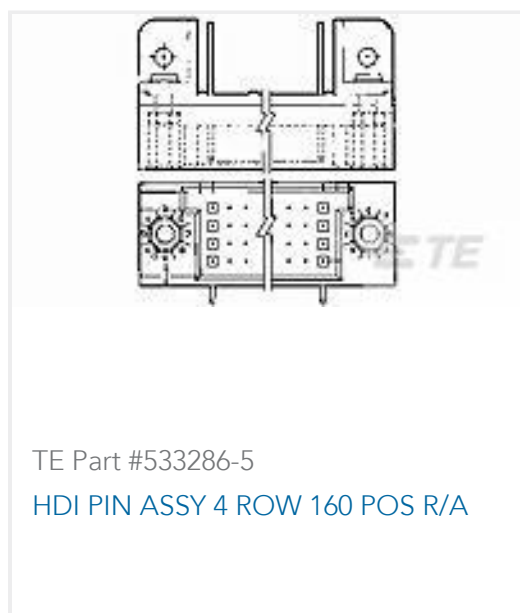
Compatible Parts



Also in the Series | **AMP Mezalok**



Customers Also Bought





Documents

Product Drawings

[Skt Assy, 320, LF, 30 AU, 18mm, Mezalok](#)

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_1-2102430-2_D.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-2102430-2_D.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1-2102430-2_D.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[Mezalok Connector Brochure](#)

English

Product Specifications

[Product Specification](#)

English